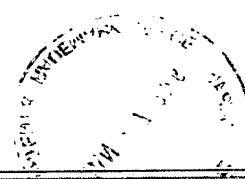


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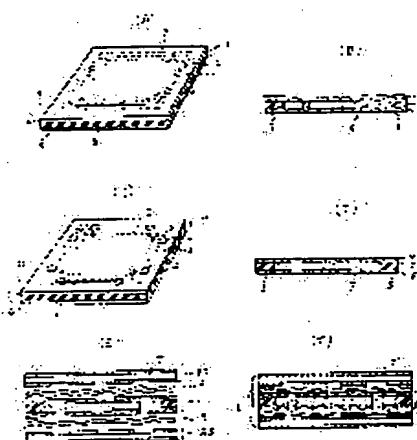
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(54) MANUFACTURE OF MULTILAYERED PRINTED CIRCUIT BOARD

(57)Abstract:

PURPOSE: To prevent a metal core from being exposed by a method wherein a metal core inner layer plate is formed, then a peripheral section and A product pattern connecting section are cut off by a drilling operation or the like, and insulating resin is made to fill holes bored in a multi-stratification bonding process.

CONSTITUTION: A metal core 5 and a prepreg resin 6 are made to be formed into one piece for the formation of a metal inner layer plate 1. Holes are bored in a connecting section 4 with a NC drill, and then a peripheral section is made to be cut off the product pattern connecting section 4. A product pattern section 2 and the peripheral section 3 both of the metal core 5 are connected together through the resin 6. A metal core inner layer plate 1' is bonded to other inner layer circuit plates 8a and 8b through a prepreg 9 for multi-stratification of them so as to form a multilayered printed circuit plate 10. Holes drilled in the connecting section 4 are filled with the resin 9 in a multi-stratification bonding process. By these processes, the exposure of the metal core can be prevented.



LEGAL STATUS

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